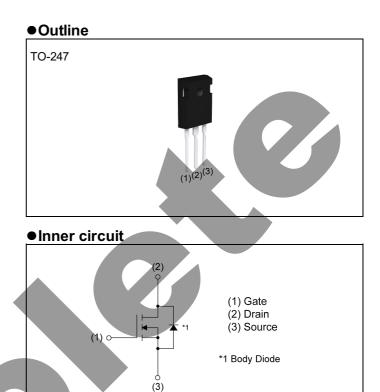


R6547ENZ1

Nch 650V 47A Power MOSFET

V <sub>DSS</sub>	650V
R <sub>DS(on)</sub> (Max.)	0.080Ω
I <sub>D</sub>	±47A
P <sub>D</sub>	480W



# Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating ; RoHS compliant

<ul> <li>Application</li> </ul>
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Switching

	Pacl	kaging	specifications
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Tube
C9
R6547ENZ1
450

# • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V <sub>DSS</sub>	650	V
Continuous drain current $(T_c = 2)$	5°C)	۱ <sub>D</sub> *1	±47	А
Pulsed drain current		I <sub>DP</sub> *2	±141	А
Cata Source veltage	static		±20	V
Gate - Source voltage	AC(f>1Hz)	$V_{GSS}$	±30	V
Avalanche current, single pulse		I <sub>AS</sub>	9.3	А
Avalanche energy, single pulse		$E_{AS}^{*3}$	1222	mJ
Power dissipation ( $T_c = 25^{\circ}C$ )		P <sub>D</sub>	480	W
Junction temperature		Tj	150	°C
Operating junction and storage to	emperature range	T <sub>stg</sub>	-55 to +150	°C

# •Thermal resistance

Deremeter	Cumph of	Values			Lincit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}^{*4}$	-	-	0.26	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	30	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# • Electrical characteristics ( $T_a = 25^{\circ}C$ )

Parameter	Sumbol	Canditiana	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, 1 <sub>D</sub> = 1mA	650	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 650V, V_{GS} = 0V$ $T_j = 25^{\circ}C$ $T_i = 125^{\circ}C$	-	-	100 1000	μΑ
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 1.72 \text{mA}$	2	-	4	V
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	$V_{GS} = 10V, I_D = 25.8A$ T <sub>j</sub> = 25°C T <sub>j</sub> = 125°C	-	0.070 0.140	0.080	Ω
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	1	-	Ω



# • Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Sumbol	Conditions	Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	3800	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	4000	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	360	-	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 300$ V, $V_{GS}$ = 10V	-	40		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 23.5A	-	120	-	
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 12.7\Omega$	-	280	-	ns
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	110	-	

# • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

• Gate charge characteristics ( $T_a = 25^{\circ}C$ )						
Parameter	Symbol	Conditions		Values		Unit
Farameter	Зушоо	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ~ 300V	-	150	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 47A	-	22	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	80	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≃ 300V, I <sub>D</sub> = 47A	-	5.9	-	V

\*1 Limited only by maximum channel temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L $\doteqdot$ 20mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>j</sub>=25°C

\*4 T<sub>C</sub>=25°C

\*5 Pulsed





# •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Source current	ا <sub>S</sub> *1	• T <sub>C</sub> = 25°C	-	-	47	А
Pulsed source current	$I_{SP}^{*2}$	1 <sub>C</sub> - 25 C	-	-	141	А
Source-Drain voltage	$V_{SD}^{*5}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 47A	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *5		-	740	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	I <sub>S</sub> = 47A di/dt = 100A/µs	-	18.5	-	μC
Peak reverse recovery current	۲ <mark>"*</mark> 5		-	50	_	А

5

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# • Electrical characteristic curves

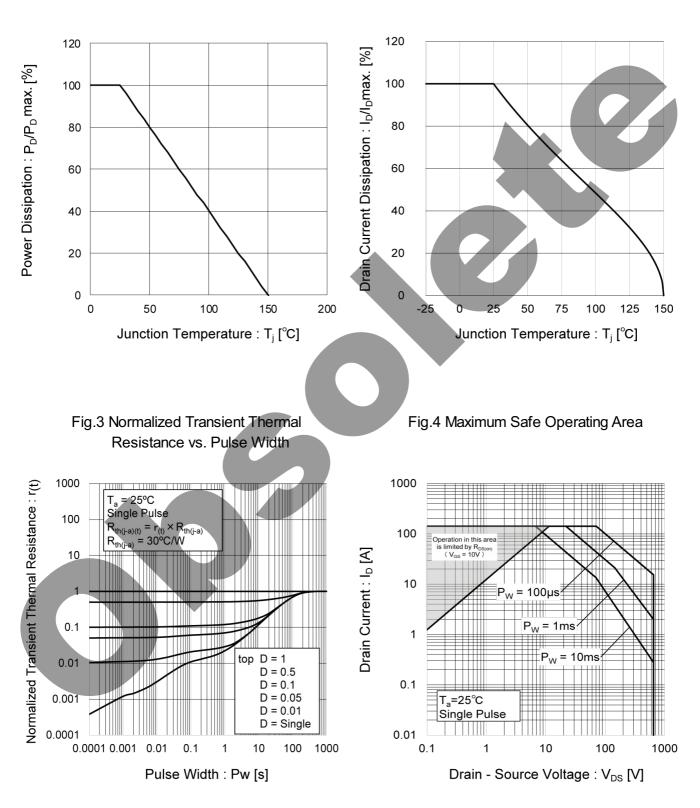


Fig.1 Power Dissipation Derating Curve

Fig.2 Drain Current Derating Curve

# Electrical characteristic curves

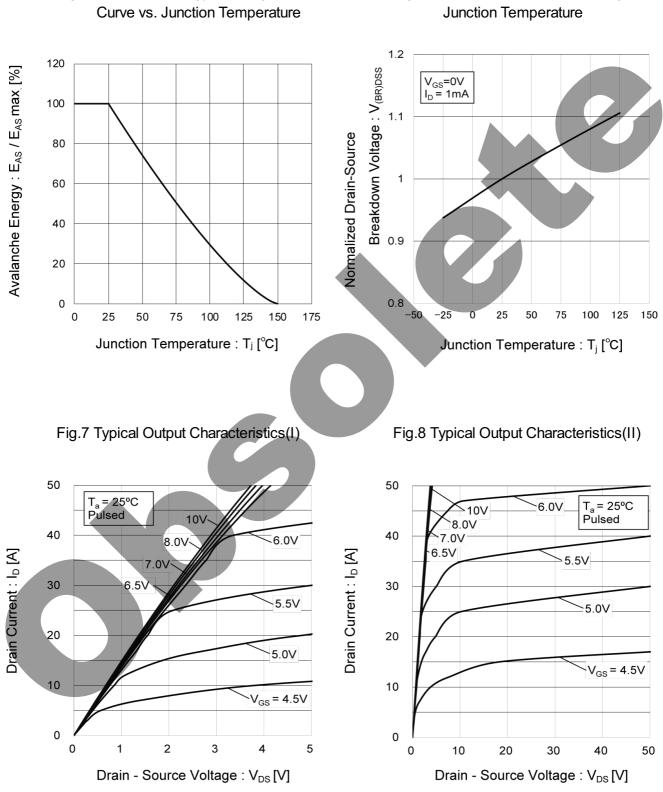


Fig.5 Avalanche Energy Derating

Fig.6 Normalized Breakdown Voltage vs.

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# •Electrical characteristic curves

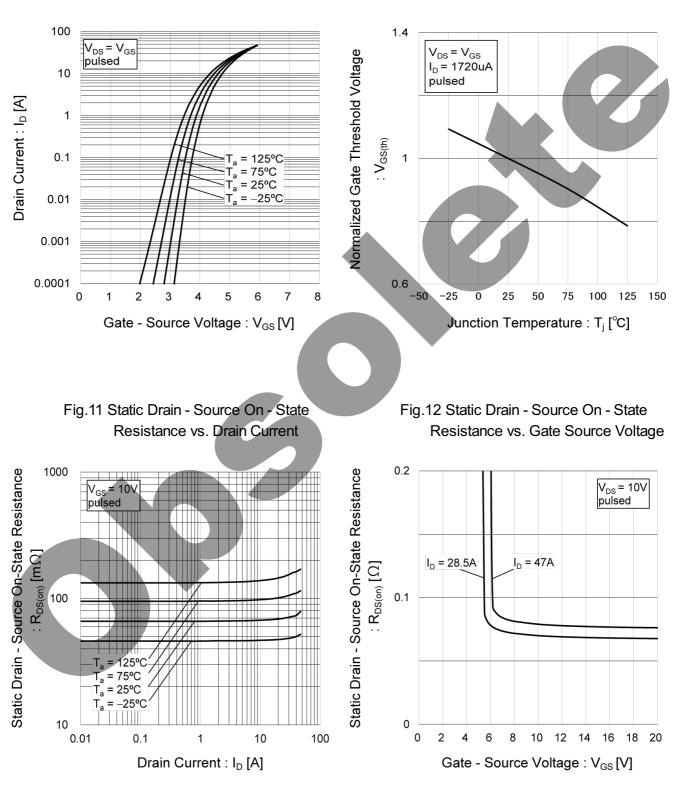
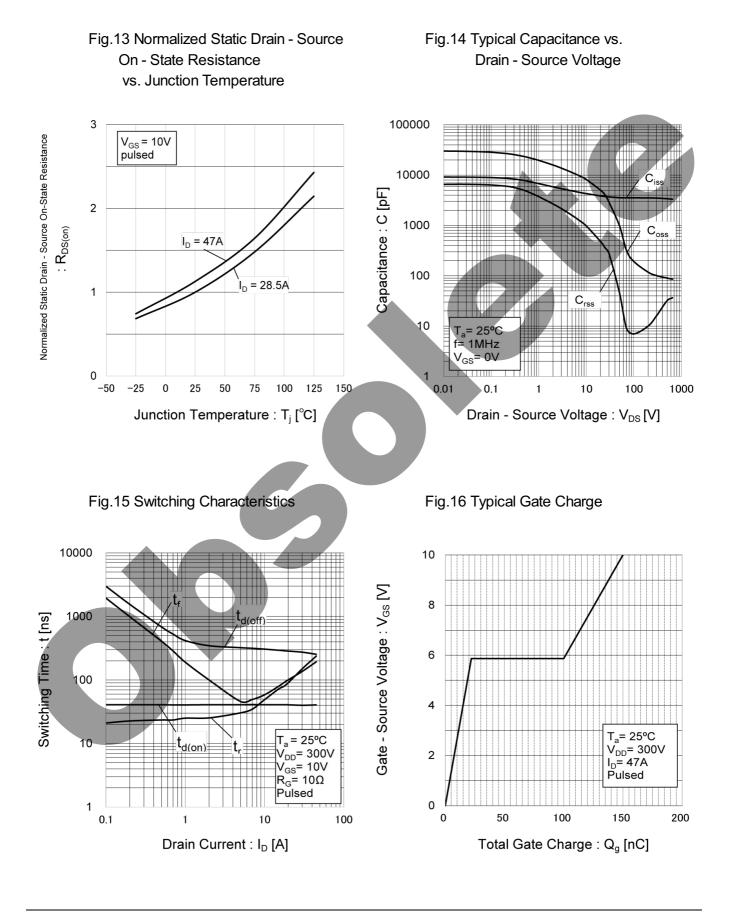


Fig.9 Typical Transfer Characteristics

Fig.10 Normalized Gate Threshold . Voltage vs Junction Temperature

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# • Electrical characteristic curves



ROHM

# • Electrical characteristic curves

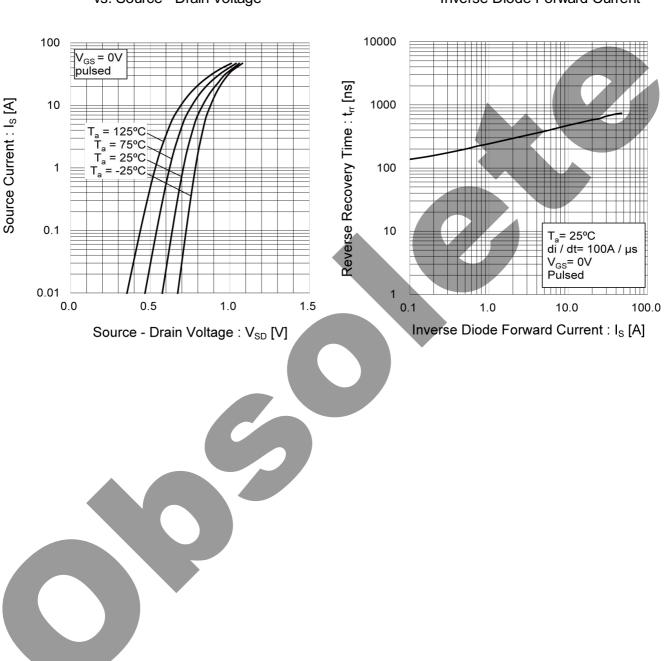
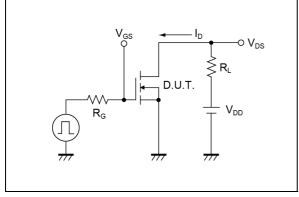


Fig.17 Source Current vs. Source - Drain Voltage Fig.18 Reverse Recovery Time vs. Inverse Diode Forward Current

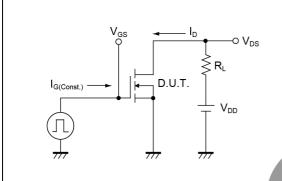


# Measurement circuits





## Fig.2-1 Gate Charge Measurement Circuit



## Fig.3-1 Avalanche Measurement Circuit

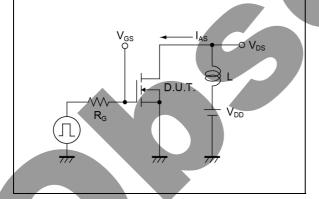


Fig.4-1 trr Measurement Circuit

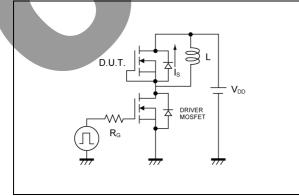
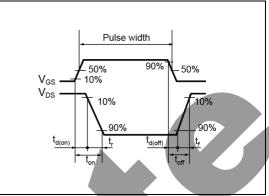
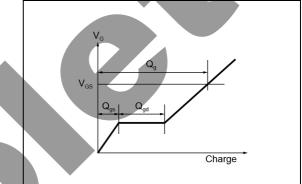


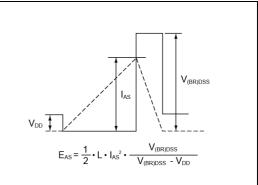
Fig.1-2 Switching Waveforms



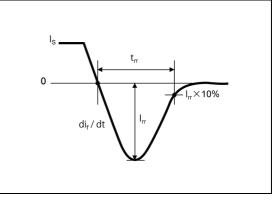




# Fig.3-2 Avalanche Waveform



## Fig.4-2 trr Waveform





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(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSI	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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